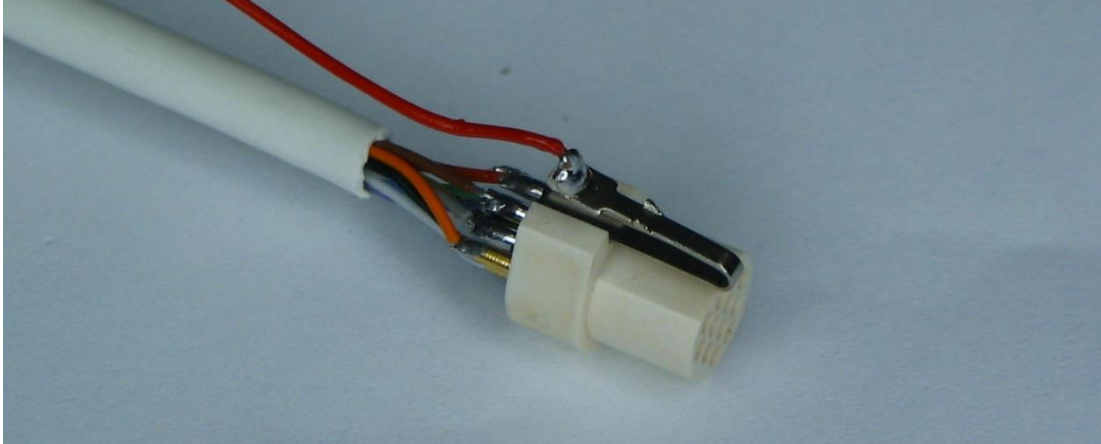
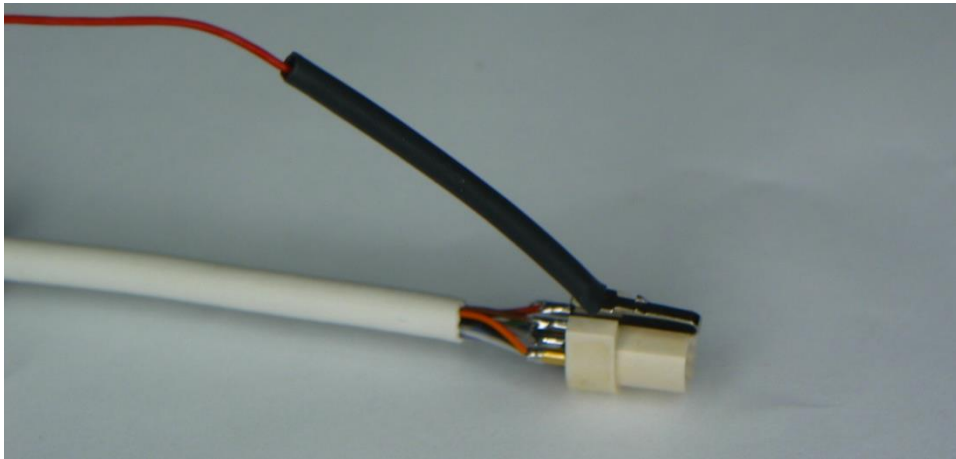


1. Using the 30 AWG wire provided, solder to the clip as shown below.



2. Add heat shrink provided, making sure to cover the solder joint.

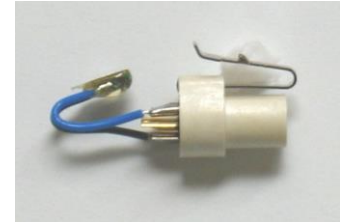


3. Heat and bend as shown below.

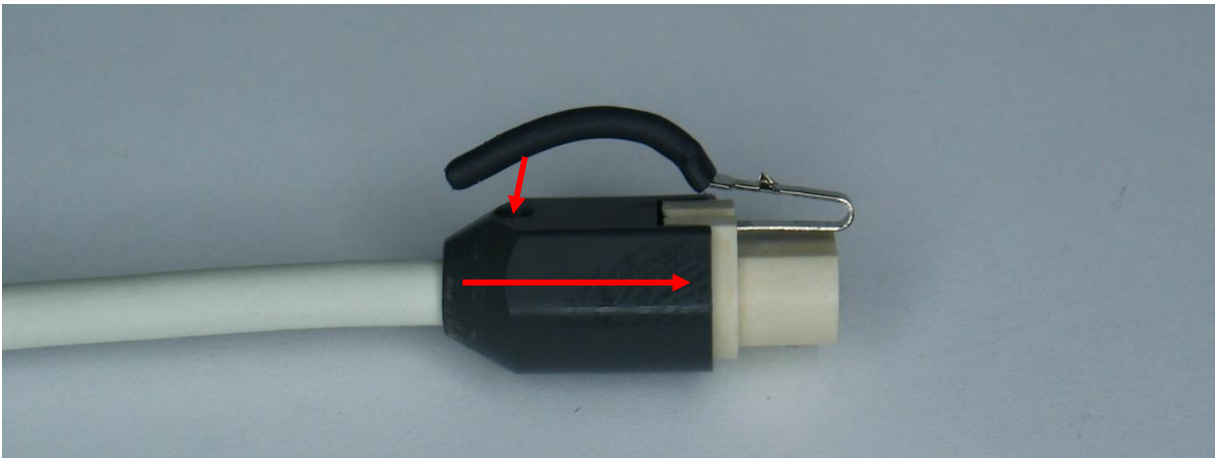


SLICE Back Shell Assembly Procedure

4. Apply a fair amount of thick epoxy (Loctite E-20HP Hysol DTS P/N: 99000-00217 recommended) to the wires and cable jacket in the area indicated below. If a sensor ID assembly is installed, fold it so that the PCB is close to but not touching the contacts and apply the epoxy as usual.



5. Slide the back shell over the uncured epoxy and firmly seat it against the connector. Carefully wipe away any excess epoxy. Trim heat shrink. Apply epoxy to unattached end of heat shrink and insert into hole in back shell. Let cure overnight.



Revision History

Rev	Date	By	Description
2			
1	15 Aug 2017	TR	Updated epoxy to Loctite E-20HP Hysol DTS P/N: 99000-00217
0	12 Jun 2009	EK	Initial release.